



描述 / Descriptions

肖特基整流二极管，薄型 SOD-323FL 封装。

Schottky Barrier Rectifiers, SOD-323FL thin package.

特征 / Features

低功耗，高效率，高电流，正向压降低，浪涌能力高，适用于低压，高频逆变器。无卤产品。

Low power loss, high efficiency . High current capability , low forward voltage drop , High surge capability, For use in low voltage, high frequency inverters . Halogen free product.

用途 / Applications

一般用途。 .

General purpose.

内部等效电路 / Equivalent Circuit

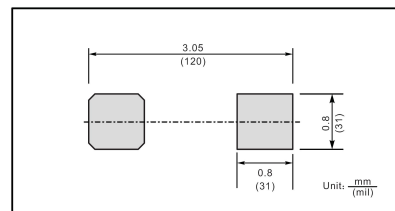


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating			单位 Unit
		B5817WSFL	B5818WSFL	B5819WSFL	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	30	40	V
Maximum RMS voltage	V_{RMS}	14	21	28	V
Maximum DC Blocking Voltage	V_{DC}	20	30	40	V
Maximum Average Forward Rectified Current	$I_F (AV)$	1.0			A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method)	I_{FSM}	25			A
Typical Junction Capacitance	C_i	110			pF
Storage and Operating Junction Temperature Range	T_J, T_{stg}	-55~+125			°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating			单位 Unit
			B5817WSFL	B5818WSFL	B5819WSFL	
Maximum Instantaneous Forward Voltage	V_F	$I_F=1.0A$	0.45	0.55	0.60	V
		$I_F=3.0A$	0.75	0.875	0.90	
Maximum Instantaneous Reverse Current at Rated DC Reverse Voltage	I_R	$T_a=25^{\circ}C$	1.0			mA
		$T_a=100^{\circ}C$	10			mA

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

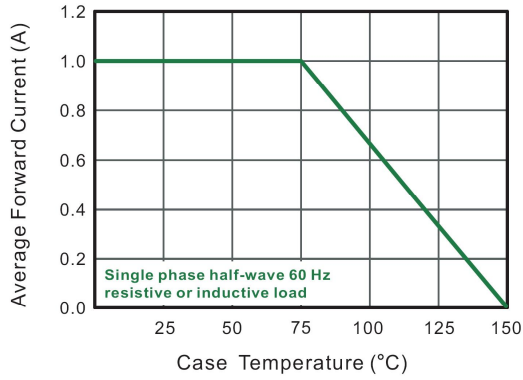


Fig.2 Typical Reverse Characteristics

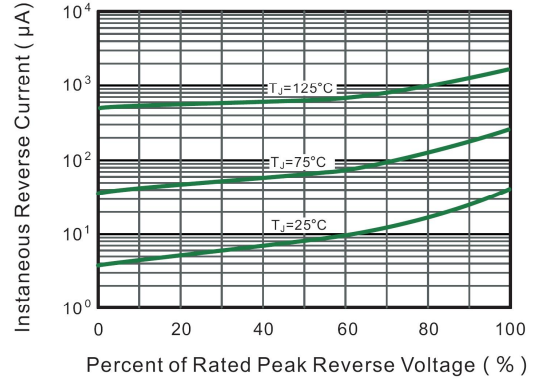


Fig.3 Typical Forward Characteristic

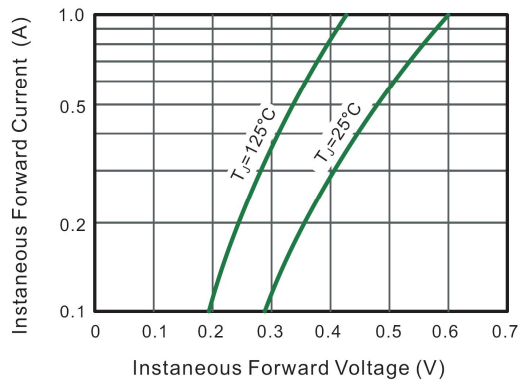


Fig.4 Typical Junction Capacitance

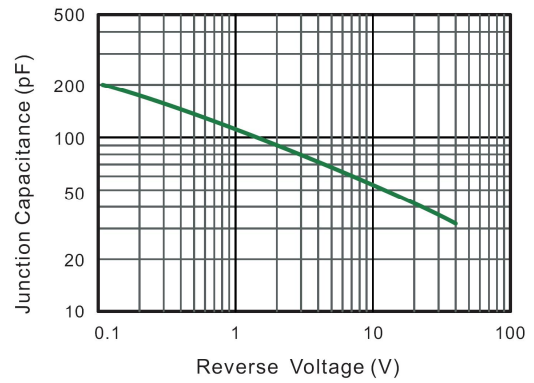
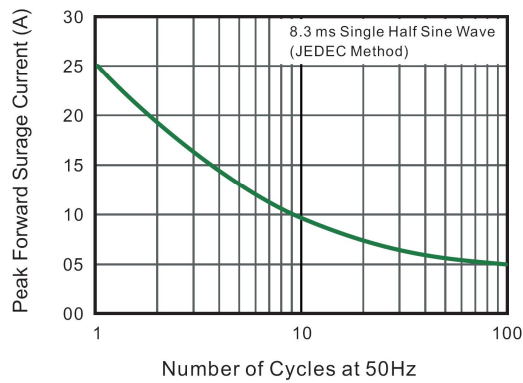


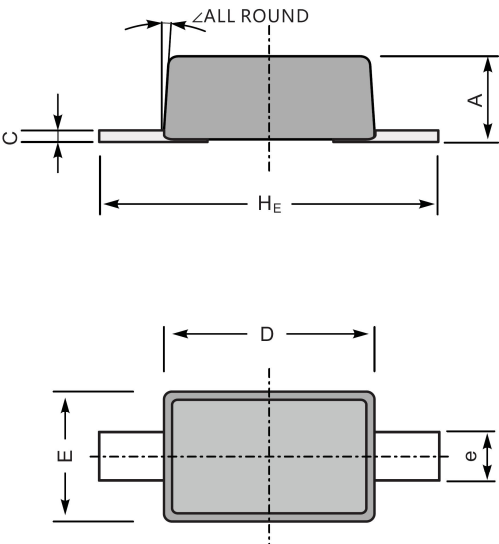
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions

Plastic surface mounted package; 2 leads

SOD-323FL



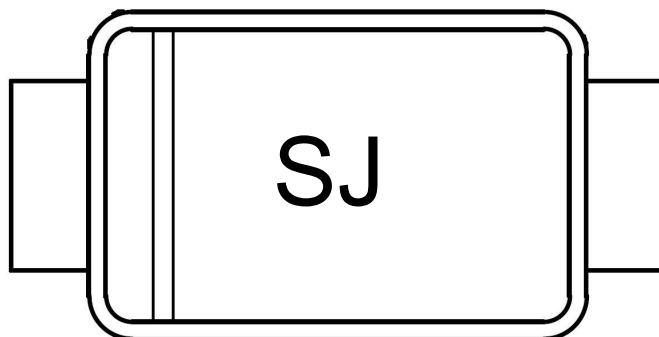
UNIT		A	C	D	E	e	H _E	$\angle$
mm	max	1.0	0.25	1.8	1.35	0.4	2.7	8°
	min	0.8	0.05	1.6	1.15	0.25	2.3	
mil	max	39	9.8	71	53	18	106	
	min	31	2.0	63	45	10	91	

印章说明 / Marking Instructions

Marking

Type number	Marking code
B5817WSFL	SJ
B5818WSFL	SK
B5819WSFL	SL

印章说明 / Marking Instructions

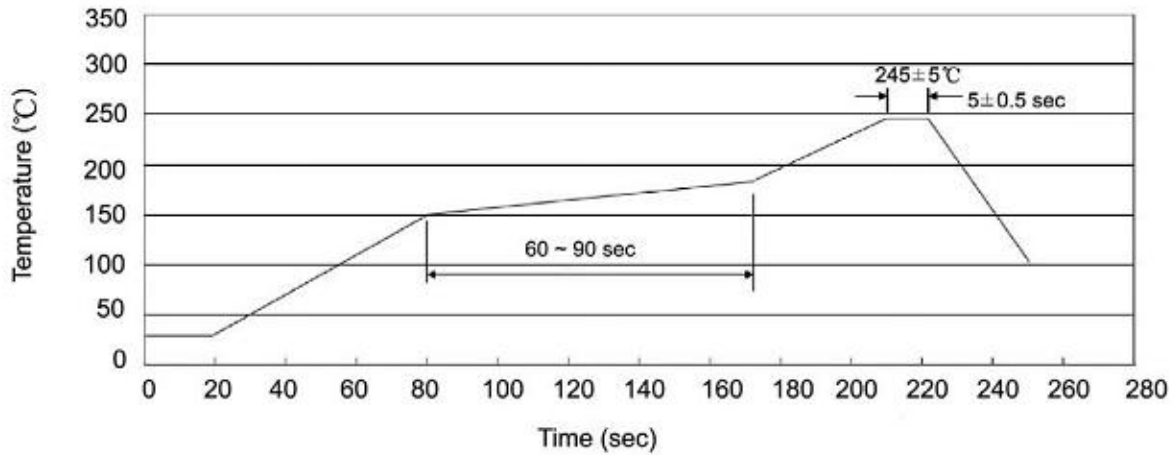


说明：

SJ： 为型号代码

Note:

SJ： Product Type Code


回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323FL	3000	8	24000	6	144000	7" ×11	185X180X105	390X385X205

使用说明 / Notices